PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Niloy Mukherjee	01/05/2012
Matthew V Metz	01/06/2012
James M Powers	01/05/2012
Van H Le	01/05/2012
Benjamin Chu-Kung	01/05/2012
Mark R Lemay	01/06/2012
Marko Radosavljevic	01/05/2012
Niti Goel	01/10/2012
Loren Chow	01/05/2012
Peter G Tolchinsky	01/05/2012
Jack T Kavalieros	01/06/2012
Robert S Chau	01/06/2012

RECEIVING PARTY DATA

Name:	Intel Corporation
Street Address:	2200 Mission College Boulevard
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95052

PROPERTY NUMBERS Total: 1

Property Type	Number
PCT Number:	US1167661

CORRESPONDENCE DATA

Fax Number: (408)720-8383 Phone: 4087208300

Email: teresa_mattox@bstz.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent PATENT

REEL: 027569 FRAME: 0573

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via US Mail.

Correspondent Name: Blakely, Sokoloff, Taylor & Zafman LLP

Address Line 1: 1279 Oakmead Parkway

Address Line 4: Sunnyvale, CALIFORNIA 94085

ATTORNEY DOCKET NUMBER: 42P38778PCT

NAME OF SUBMITTER: Teresa Mattox

Total Attachments: 11

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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Niloy Mukherjee, Matthew V. Metz, James M. Powers, Van H. Le, Benjamin Chu-Kung, Mark R. Lemay, Marko Radosavljevic, Niti Goel, Loren Chow, Peter G. Tolchinsky, Jack T. Kavalieros, Robert S. Chau

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard. Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the International application entitled:

METHODS OF FORMING HETERO-LAYERS WITH REDUCED SURFACE ROUGHNESS AND BULK DEFECT DENSITY ON NON-NATIVE SURFACES AND THE STRUCTURES FORMED THEREBY

(I hereby authorize and request my attorney, associated with Customer Number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on December 28, 2011 as

International Application Number PCT/US2011/067661 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below.

and in and to said International application and all related applications (e.g. national phase applications, divisional applications, continuation applications, reexaminations, reissues, and the like) that have been or shall be filed in the United States and/or all foreign countries on said inventions and improvements, as well as in and to all rights of priority resulting from the filing of said International application:

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its

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successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the un dersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

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17 nerja	0/2/05/2012
Niloy Mukherjee	6/8/05/2012 (Today's Date)
Matthew V. Metz.	1/6/12
Matthew V. Metz	(Today's Date)
James M. Powers	(Today's Date)
	,
Van H. Le	$\frac{1/5/12}{\text{(Today's Date)}}$
Van H. Le	(Today's Date)
Benjamin Chu-Kung	1/5/12
Benjamin Chu-Kung	(Today's Date)
Mark R Elman	(Today's Date)
Mark R. Lemay	(Today's Date)
Marko Radosavljevic	1/5/12
Marko Radosavljevic	<u> </u>
Niti Goel	(Today's Date)
WORLD AND THE STREET ST	
Loren Chow	(Today's Date)
MN Alexander	115/12
Peter G. Tolchinsky	1/5//2 (Today's Date)

(Today's Date)

Robert S. Chau

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Page 3 of 3

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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

	Niloy Mukherjee	(Today's Date)
Jan M	Matthew V. Metz	(Today's Date) //5/20/2_ (Today's Date)
	James M. Powers	(Today's Date)
	Van H. Le	(Today's Date)
	Benjamin Chu-Kung	(Today's Date)
	Mark R. Lemay	(Today's Date)
	Marko Radosavljevic	(Today's Date)
	Niti Goel	(Today's Date)
	Loren Chow	(Today's Date)
	Peter G. Tolchinsky	(Today's Date)

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Page 2 of 3

	·
Jack T. Kavalieros	(Today's Date)
Robert S. Chau	(Today's Date)

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Marko Radosavljevic	(Today's Date)
Niti Goel	(Today's Date)
Avocultion Loren Chow	Junuary 5,2012 (Today's Date)
Peter G. Tolchinsky	(Today's Date)

Page 2 of 3

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	Attorney Docket No.: P38778PCT
Jack T. Kavalieros	(Today's Date)
Robert S. Chau	(Today's Date)

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RECORDED: 01/20/2012